DEPARTMENT OF
COMPUTER SCIENCE

TEXAS TECH
Whitacre College of Engineering

AI for Social Good in the Era of Large Language Models

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Tuesday, October 22, 2024
3:30 p.m.
Zoom:
https://texastech.zoom.us/j/95383054613?pwd=ud5nurbPfmobNBdKB4w8RjPpX8cnZ6.1
Meeting ID: 953 8305 4613
Passcode: 263430

Abstract: In the era of large language models (LLMs), the landscape of artificial intelligence has transformed dramatically, offering unprecedented opportunities for social impact. This talk will discuss the potential of LLMs to drive significant advancements in areas critical for social good. I will discuss the innovative applications of these models in diverse fields, such as fighting online hate and making games safer for kids. The talk will also critically examine the safety/security challenges and responsibilities inherent in deploying LLMs. By highlighting both the successes and challenges, this talk aims to foster a nuanced understanding of how LLMs can be safely and effectively utilized for the betterment of society.

Bio: Hongxin Hu is a Professor and Associate Chair of the Department of Computer Science and Engineering at University at Buffalo, SUNY. He is a recipient of the NSF CAREER Award (2019) and Amazon Research Award (2022). His research spans security, machine learning, and networking. He has participated in multiple cross-university, cross-disciplinary projects funded by NSF. His research has also been funded by NSA, U.S. Army, USDOT, Google, VMware, Amazon, etc. He has published over 150 refereed technical papers, many of which appeared in top-tier conferences such as S&P, CCS, USENIX Security, NDSS, SIGCOMM, NSDI, NeurIPS, ICML, and CHI, and well-recognized journals such as IEEE TIFS, IEEE TDSC, IEEE/ACM TON, and IEEE TKDE. He is the recipient of ACM SACMAT Test-of-Time Award in 2024, and the Best Paper Awards from ACM ASIACCS (2022), ACSAC (2020), IEEE ICC (2020), ACM SIGCSE (2018), and ACM CODASPY (2014). His research has won the First Place Award in ACM SIGCOMM 2018 SRC. His research has also been featured by the IEEE Special Technical Community on Social Networking and received 50+ press coverage including ACM TechNews, InformationWeek, Slashdot, etc.